This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

PCN Title:	ADV7844KBCZ-5 Alternate Assembly Location
Publication Date:	07-Mar-2011
Effectivity Date:	05-Jun-2011 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Initial Release

Description Of Change

STATSChipPAC China (SCC) is being qualified as an alternate assembly location for the ADV7844KBCZ-5 using the following material set: Ablestik A2000B die attach and Sumitomo G770LC mold compound.

Reason For Change

To increase assembly capacity and manufacturing flexibility for the ADV7844KBCZ-5 device. STATSChipPAC China is an existing qualified site for ADI.

Impact of the change (positive or negative) on fit, form, function & reliability

The above changes will have no effect on the form, fit, function or quality of the ADV7844KBCZ-5 product.

Product Identification *(this section will describe how to identify the changed material)*

China will be marked as the country of origin on the device.

Summary of Supporting Information

Qualification is being performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Qualification Plan.

Supporting Documents

Attachment 1: Type: Qualification Plan Summary

ADI_PCN_11_0037_Rev_-_Qual Plan.pdf

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative					
Americas:	PCN_Americas@analog.com	**Europe:**	PCN_Europe@analog.com	**Japan:**	PCN_Japan@analog.com
				Rest of Asia:	PCN_ROA@analog.com

Appendix A - Affected ADI Models
Added Parts On This Revision - Product Family / Model Number (1)
ADV7844 / ADV7844KBCZ-5

Appendix B - Revision History		
Rev	**Publish Date**	**Rev Description**